

S/N 10/808,192

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Daewoong Suh

Examiner: Jonathan Johnson

Serial No.: 10/808,192

Group Art Unit: 1725

Filed: March 24, 2004

Docket: 884.C25US1

Title: SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD

Customer Number: 21186

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Restriction Requirement mailed August 16, 2006, Applicant hereby provisionally elects, with traverse, Group I (claims 1-13). **If the restriction is continued**, Applicants will cancel remaining claims 14-22 (with prejudice), and will reserve the right to reintroduce them in one or more divisional applications at a later date. Applicant also hereby provisionally elects Species Ia of Group I (claims 2-7 and 9).

The Restriction Requirement is traversed on the basis that Restriction Requirements are optional in all cases. MPEP 803. If the search and examination of an entire application can be made without serious burden, the Examiner must examine it on the merits, even though it arguably may include claims to distinct or independent inventions. MPEP 803.

All of the pending claims relate to semiconducting devices, electronic systems and methods that include (i) a motherboard that includes a first contact; (ii) an electronic package that includes a second contact bonded to the first contact; and (iii) *an interlayer diffused within the first and second contacts* such that the bonded first and second contacts have a higher melting temperature than the interlayer before being diffused into the first and second contacts. The Examiner will be looking for a motherboard, electronic package, first and second contacts and a diffused interlayer as recited in each of claims 1-22. Thus, Applicant respectfully submits that these claims can all be easily searched and examined together.

As part of maintaining the restriction, the Examiner states at page 2 of the Office Action that “In the instant case, the product as claimed can be made by a process where the contacts are premixed and do not rely on diffusion bonding.” Applicant can not see where the statement adequately indicates that claims 1-13 are distinct inventions from claims 14-22. Clarification is respectfully requested.

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In addition, Applicant also respectfully fails to see the relevance and accuracy of the statements because each of claims 1-22 recites a motherboard, electronic package, first and second contacts and a diffused interlayer. Applicant further notes the claim language in each of the claims recites (i) “melting the interlayer *to diffuse* the interlayer into the first and second contacts” as recited in claim 1; or (ii) “an interlayer *diffused* within the first and second contacts” as recited in claims 14 and 20. Therefore, the Examiner will be searching for an interlayer that is diffused into the first and second contacts when searching relative to each of the independent claims.

The Examiner is invited to telephone Applicant’s attorney at 262-646-7009 to facilitate the prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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